EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3292	438/275,257,211,216,219,221,248, 272,279,287,294,295,286,359.ccls. and @ad<="20001207"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 08:46
S2	1112	438/275,257,211,216,219,221,248, 272,279,287,294,295,286,359.ccls. and @ad<="20001207" and spacers	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:12
S3	1258	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount$3 and (underfill$3 or encapsulant or encapulating or resin) and (heat$3 or temperature or anneal$3) and (curing or cured)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:16
S4	972	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount$3 and (underfill$3 or encapsulant or encapulating or resin) and (heat$3 or temperature or anneal$3) and (curing or cured) and expos$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:16
S5	584	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount$3 and (underfill$3 or encapsulant or encapulating or resin) and (heat$3 or temperature or anneal$3) and (curing or cured) and expos$3 and external	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:17
S6	58	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount$3 and (underfill$3 or encapsulant or encapulating or resin) and (heat$3 or temperature or anneal$3) and (curing or cured) and expos$3 and external and housing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:18

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S7	175	"438"/$.ccls. and @ad<="20050208" and (die or chip) and mount$3 and (underfill$3 or encapsulant or encapulating or resin) and (heat$3 or temperature or anneal$3) and (curing or cured) and expos$3 and external and housing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:18
S8	491	"257"/$.ccls. and @ad<="20050208" and (die or chip) and mount$3 and (underfill$3 or encapsulant or encapulating or resin) and (heat$3 or temperature or anneal$3) and (curing or cured) and expos$3 and external and housing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:26
S9	1	11/281502	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:26
S10	22	"438"/$.ccls. and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:19
S11	39	"257"/$.ccls. and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:17
S12	1	"257"/$.ccls. and @ad<="20011004" and (spacers near interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:15
S13	1	"438"/$.ccls. and @ad<="20011004" and (spacers near interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:15

S14	1	semiconductor and @ad<="20011004" and (spacers near interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:16
S15	39	"257"/$.ccls. and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:15
S16	48	semiconductor and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:18
S17	281	"438"/$.ccls. and @ad<="20011004" and (spacers with interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:03
S18	50	"438"/$.ccls. and @ad<="20011004" and (sidewall near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:20
S19	71	"257"/$.ccls. and @ad<="20011004" and (sidewall near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:19
S20	31	"438"/$.ccls. and @ad<="20011004" and (spacers with interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:04

S21	34	"257"/$.ccls. and @ad<="20011004" and (spacers with interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:04
S22	35	semiconductor and @ad<="20011004" and (spacers with interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:04